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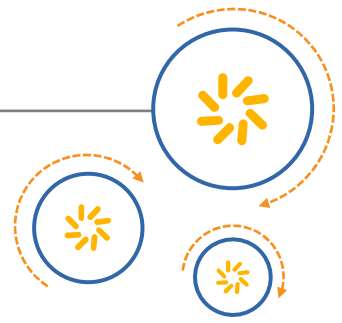
Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





RF360 Europe GmbH
A Qualcomm – TDK Joint Venture

SAW components

SAW duplexer

Small cell & femtocell
LTE band 4

Series/type:	B8033
Ordering code:	B39212B8033P810
Date:	January 11, 2018
Version:	2.1

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SAW components	B8033
SAW duplexer	1732.50 / 2132.50 MHz

Data sheet

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Data sheet

1 Application

- Low-loss SAW duplexer for LTE smallcell system (Band 4)
- Low insertion attenuation
- Low amplitude ripple
- Usable pass band 45MHz
- High power durability in downlink
- TX=DOWNLINK=2110-2155MHz
- RX=UPLINK=1710-1755MHz

2 Features

- Package size 2.5±0.1 mm × 2.0±0.1 mm
- Package height 0.5 mm (max.)
- Approximate weight 0.01 g
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 2a (MSL2a)

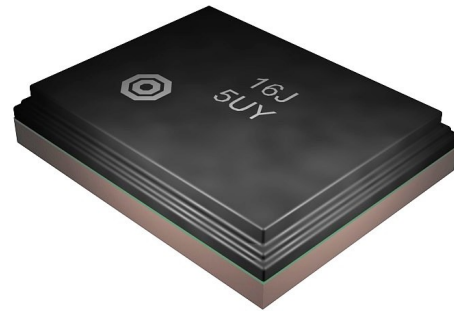


Figure 1: Picture of component with example of product marking.

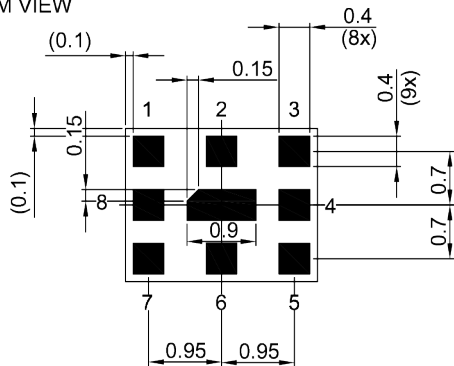
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3 Package

BOTTOM VIEW

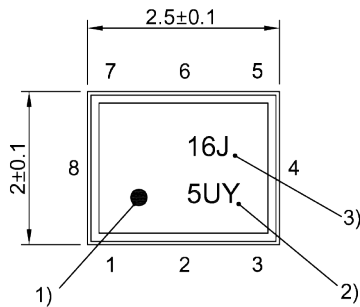


Pad and pitch tolerance ±0.05

SIDE VIEW

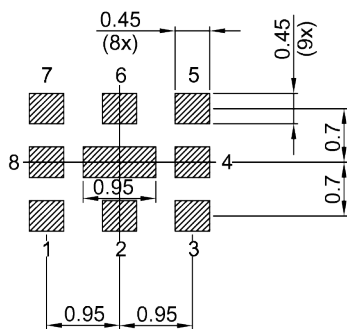


TOP VIEW



- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number

Land pattern THRU VIEW



Landing pad tolerance -0.02

Figure 2: Drawing of package with package height A = 0.5 mm (max.). See Sec. Package information (p. 26).

4 Pin configuration

- 1 TX
- 3 RX
- 6 ANT
- 2, 4, 5, 7, 8, 9 Ground

Data sheet

5 Matching circuit

- $L_{p6} = 3.3 \text{ nH}$

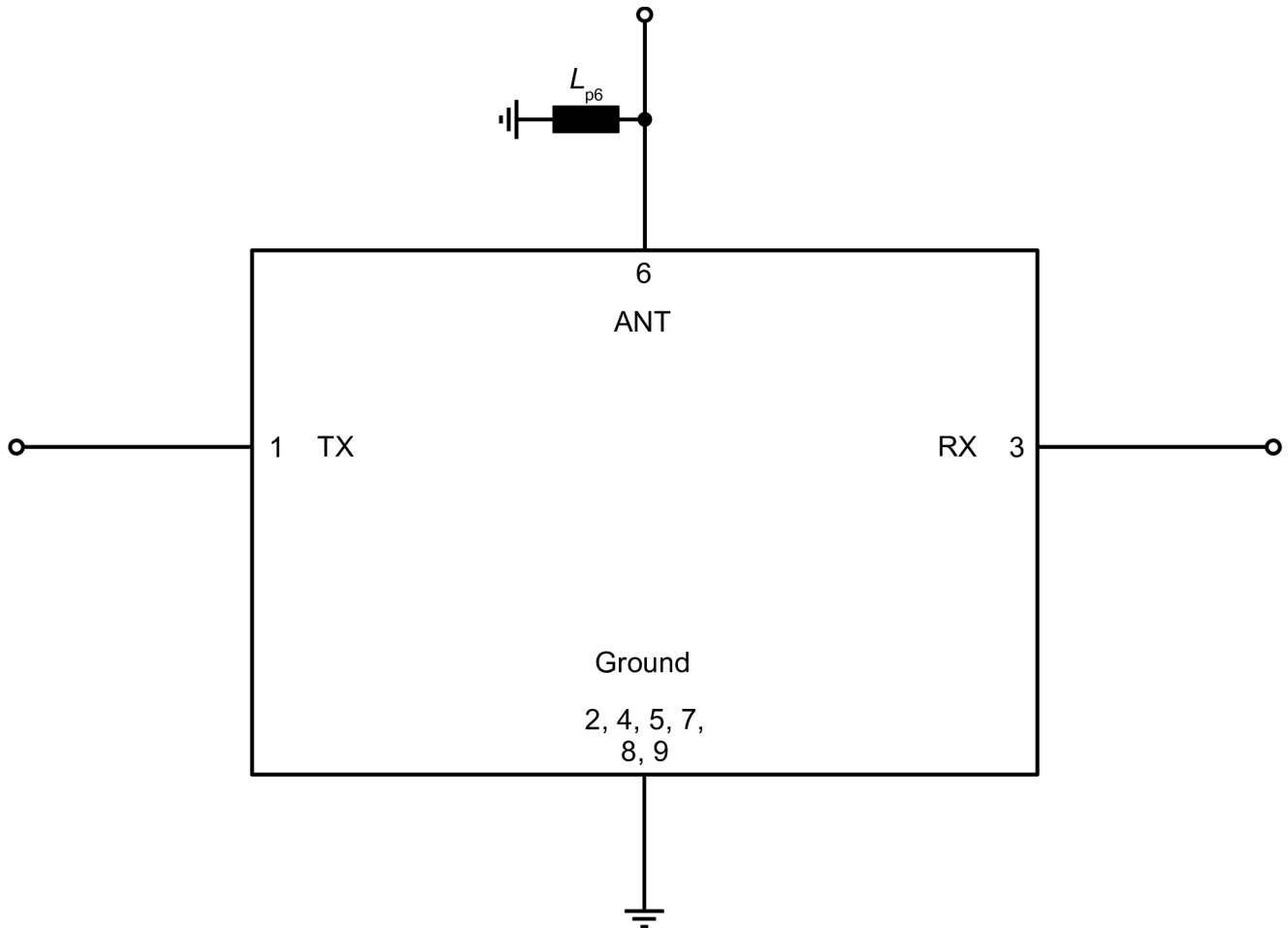


Figure 3: Schematic of matching circuit.

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6 Characteristics

6.1 TX – ANT

Temperature range for specification	T_{SPEC}	= -10 °C ... +85 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω with par. 3.3 nH ¹⁾
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics TX – ANT				min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Center frequency			f_C	—	2132.5	—	MHz
Maximum insertion attenuation	2110... 2155	MHz	α_{max}	—	1.7	2.4	dB
Amplitude ripple (p-p)	2110... 2155	MHz	$\Delta\alpha$	—	0.3	1.0	dB
Maximum VSWR			VSWR _{max}				
@ TX port	2110... 2155	MHz		—	1.3	2.0	
@ ANT port	2110... 2155	MHz		—	1.3	2.1	
Maximum error vector magnitude	2112.4... 2152.6	MHz	EVM _{max} ²⁾	—	1.2	3.0	%
Minimum attenuation			α_{min}				
	50... 1574	MHz		30	38	—	dB
	1574... 1606	MHz		35	44	—	dB
	1606... 1710	MHz		35	47	—	dB
	1710... 1755	MHz		38	47	—	dB
	1830... 1875	MHz		28	33	—	dB
	1875... 1910	MHz		20	31	—	dB
	1920... 2050	MHz		17	27	—	dB
	2180... 2200	MHz		2	7	—	dB
	2200... 2300	MHz		15	39	—	dB
	2300... 2400	MHz		30	33	—	dB
	2400... 2500	MHz		28	31	—	dB
	2500... 2690	MHz		23	27	—	dB
	2690... 3400	MHz		19	22	—	dB
	3400... 3800	MHz		10	22	—	dB
	3800... 5150	MHz		10	20	—	dB
	5150... 5180	MHz		5	20	—	dB

¹⁾ See Sec. Matching circuit (p. 6).

²⁾ Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

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Temperature range for specification	T_{SPEC}	= -40 °C ... +95 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω with par. 3.3 nH ¹⁾
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics TX – ANT				min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Center frequency			f_C	—	2132.5	—	MHz
Maximum insertion attenuation	2110... 2155	MHz	α_{max}	—	1.7	2.7	dB
Amplitude ripple (p-p)	2110... 2155	MHz	$\Delta\alpha$	—	0.3	1.3	dB
Maximum VSWR			VSWR _{max}				
@ TX port	2110... 2155	MHz		—	1.3	2.0	
@ ANT port	2110... 2155	MHz		—	1.3	2.1	
Maximum error vector magnitude	2112.4... 2152.6	MHz	EVM _{max} ²⁾	—	1.2	3.5	%
Minimum attenuation			α_{min}				
	50... 1574	MHz		30	38	—	dB
	1574... 1606	MHz		35	44	—	dB
	1606... 1710	MHz		35	47	—	dB
	1710... 1755	MHz		38	47	—	dB
	1830... 1875	MHz		28	33	—	dB
	1875... 1910	MHz		20	31	—	dB
	1920... 2050	MHz		16	27	—	dB
	2180... 2200	MHz		2	7	—	dB
	2200... 2300	MHz		10	39	—	dB
	2300... 2400	MHz		30	33	—	dB
	2400... 2500	MHz		28	31	—	dB
	2500... 2690	MHz		23	27	—	dB
	2690... 3400	MHz		19	22	—	dB
	3400... 3800	MHz		10	22	—	dB
	3800... 5150	MHz		10	20	—	dB
	5150... 5180	MHz		5	20	—	dB

¹⁾ See Sec. Matching circuit (p. 6).

²⁾ Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

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6.2 ANT – RX

Temperature range for specification	T_{SPEC}	= -10 °C ... +85 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω with par. 3.3 nH ¹⁾
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics ANT – RX				min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Center frequency			f_C	—	1732.5	—	MHz
Maximum insertion attenuation	1710... 1755	MHz	α_{max}	—	2.1	3.1	dB
Amplitude ripple (p-p)	1710... 1755	MHz	$\Delta\alpha$	—	0.6	1.6	dB
Maximum VSWR			VSWR _{max}				
@ ANT port	1710... 1755	MHz		—	1.5	2.0	
@ RX port	1710... 1755	MHz		—	1.7	2.1	
Maximum error vector magnitude	1712.4... 1752.6	MHz	EVM _{max} ²⁾	—	1.2	3.0	%
Minimum attenuation			α_{min}				
	50... 1500	MHz		40	53	—	dB
	1500... 1560	MHz		45	51	—	dB
	1560... 1675	MHz		21	37	—	dB
	1675... 1680	MHz		15	35	—	dB
	1775... 1805	MHz		3	11	—	dB
	1805... 1830	MHz		20	42	—	dB
	1830... 1880	MHz		34	44	—	dB
	1880... 1910	MHz		34	44	—	dB
	1920... 1980	MHz		38	44	—	dB
	1980... 2110	MHz		20	48	—	dB
	2110... 2155	MHz		49	52	—	dB
	2155... 2300	MHz		45	50	—	dB
	2300... 2500	MHz		38	50	—	dB
	2500... 3800	MHz		40	53	—	dB
	3800... 4310	MHz		32	42	—	dB
	4310... 5265	MHz		29	42	—	dB

¹⁾ See Sec. Matching circuit (p. 6).

²⁾ Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

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Temperature range for specification	T_{SPEC}	= -40 °C ... +95 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω with par. 3.3 nH ¹⁾
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics ANT – RX				min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Center frequency			f_C	—	1732.5	—	MHz
Maximum insertion attenuation	1710... 1755	MHz	α_{max}	—	2.1	3.8	dB
Amplitude ripple (p-p)	1710... 1755	MHz	$\Delta\alpha$	—	0.6	2.3	dB
Maximum VSWR			VSWR _{max}				
@ ANT port	1710... 1755	MHz		—	1.5	2.5	
@ RX port	1710... 1755	MHz		—	1.7	2.8	
Maximum error vector magnitude	1712.4... 1752.6	MHz	EVM _{max} ²⁾	—	1.2	4.0	%
Minimum attenuation			α_{min}				
	50... 1500	MHz		40	53	—	dB
	1500... 1560	MHz		45	51	—	dB
	1560... 1675	MHz		21	37	—	dB
	1675... 1680	MHz		15	35	—	dB
	1775... 1805	MHz		3	11	—	dB
	1805... 1830	MHz		20	42	—	dB
	1830... 1880	MHz		34	44	—	dB
	1880... 1910	MHz		34	44	—	dB
	1920... 1980	MHz		38	44	—	dB
	1980... 2110	MHz		20	48	—	dB
	2110... 2155	MHz		49	52	—	dB
	2155... 2300	MHz		45	50	—	dB
	2300... 2500	MHz		38	50	—	dB
	2500... 3800	MHz		40	53	—	dB
	3800... 4310	MHz		32	42	—	dB
	4310... 5265	MHz		29	42	—	dB

¹⁾ See Sec. Matching circuit (p. 6).

²⁾ Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

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6.3 TX – RX

Temperature range for specification	T_{SPEC}	= -10 °C ... +85 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω with par. 3.3 nH ¹⁾
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics TX – RX			min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Minimum isolation	α_{min}	1710... 1755 MHz	45	49	—	dB
		2110... 2155 MHz	48	52	—	dB

¹⁾ See Sec. Matching circuit (p. 6).

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Temperature range for specification	T_{SPEC}	= -40 °C ... +95 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω with par. 3.3 nH ¹⁾
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics TX – RX			min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Minimum isolation	α_{min}	1710... 1755 MHz	44	49	—	dB
		2110... 2155 MHz	46	52	—	dB

¹⁾ See Sec. Matching circuit (p. 6).

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7 Maximum ratings

Operable temperature	$T_{OP} = -40\text{ °C} \dots +95\text{ °C}$	
Storage temperature	$T_{STG}^{1)} = -40\text{ °C} \dots +95\text{ °C}$	
DC voltage	$ V_{DC} ^{2)} = 0\text{ V}$	
ESD voltage		
	$V_{ESD}^{3)} = 50\text{ V}$	Machine model.
	$V_{ESD}^{4)} = 175\text{ V}$	Human body model.
Input power	P_{IN}	
@ TX port: 2110 ... 2155 MHz	27.4 dBm ⁵⁾	Pin average – Peak 38.4dBm LTE 5MHz downlink for 100000 h @ 55 °C. Source and load impedance 50Ω.
@ elsewhere	10 dBm	
Operating Lifetime with output power at antenna		
@ 2110 ... 2155 MHz	24 dBm ⁶⁾	Continuous wave for 100000 h @ 55 °C.

¹⁾ Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.

²⁾ In case of applied DC voltage blocking capacitors are mandatory.

³⁾ According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.

⁴⁾ According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse.

⁵⁾ Time to failure (TTF) according to accelerated power durability test, and wear out models.

⁶⁾ According to accelerated High Temperature Operating Life (HTOL) test.

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8 Transmission coefficients

8.1 TX – ANT

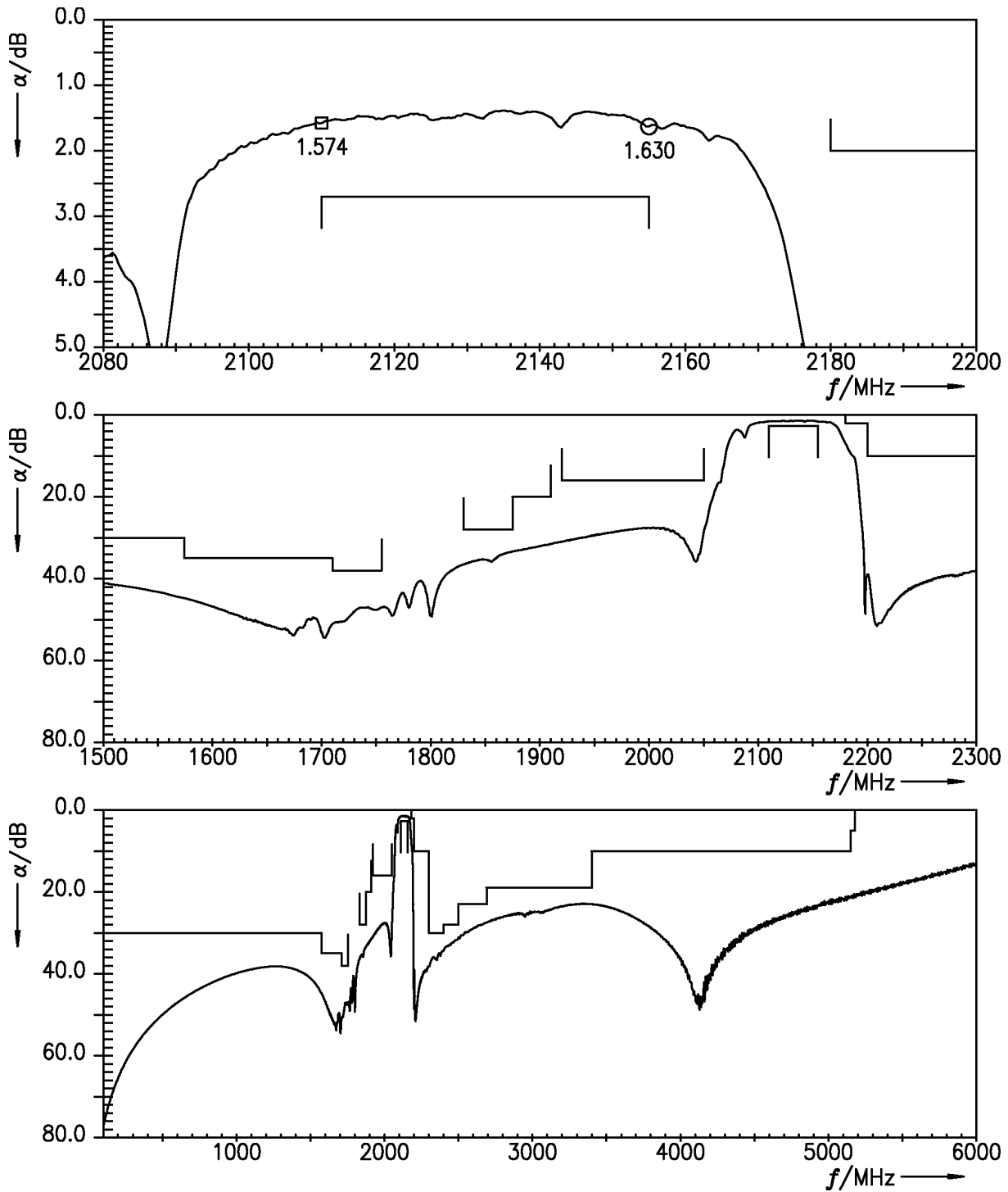


Figure 4: Attenuation TX – ANT.

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8.2 ANT – RX

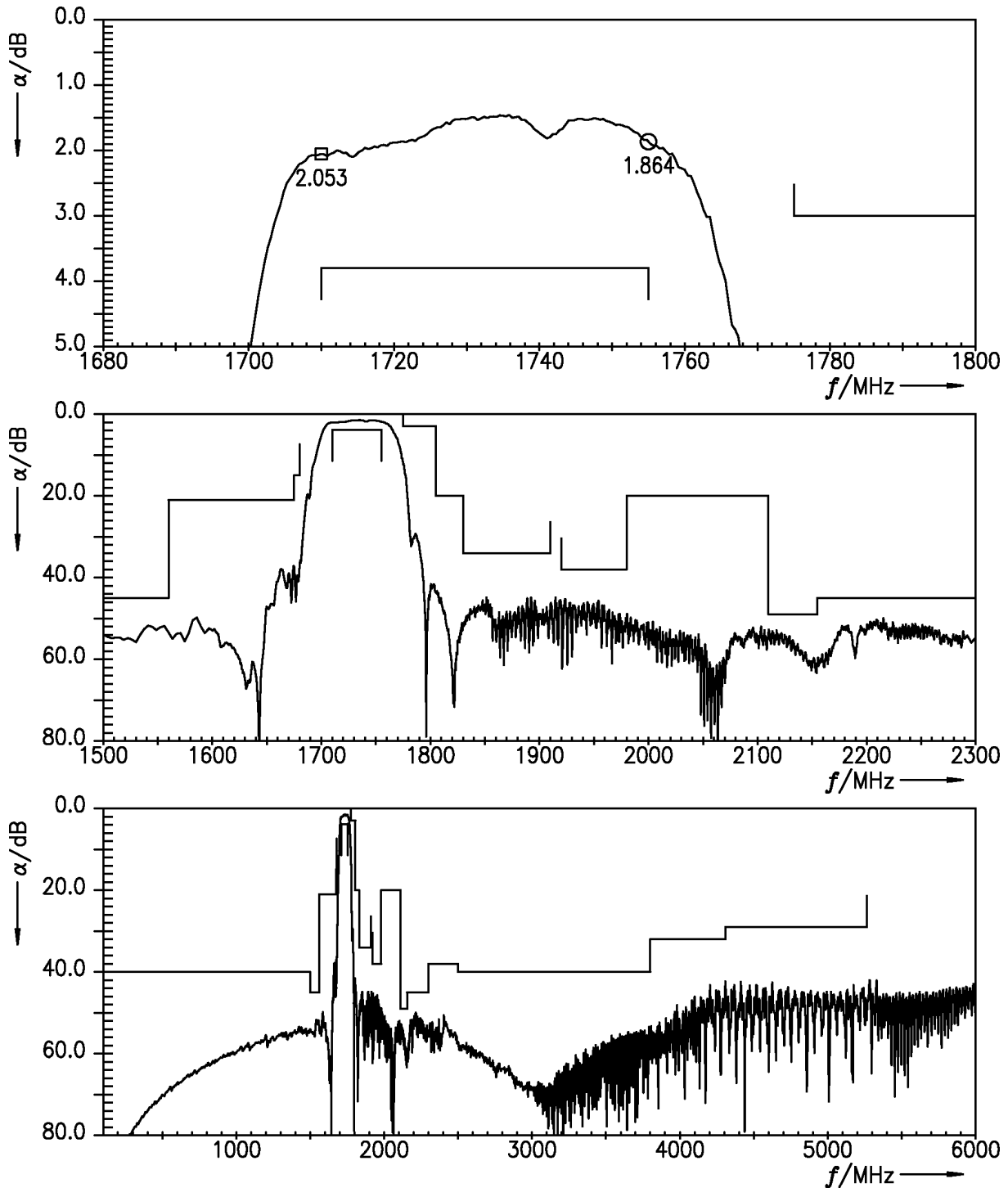


Figure 5: Attenuation ANT – RX.

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8.3 TX – RX

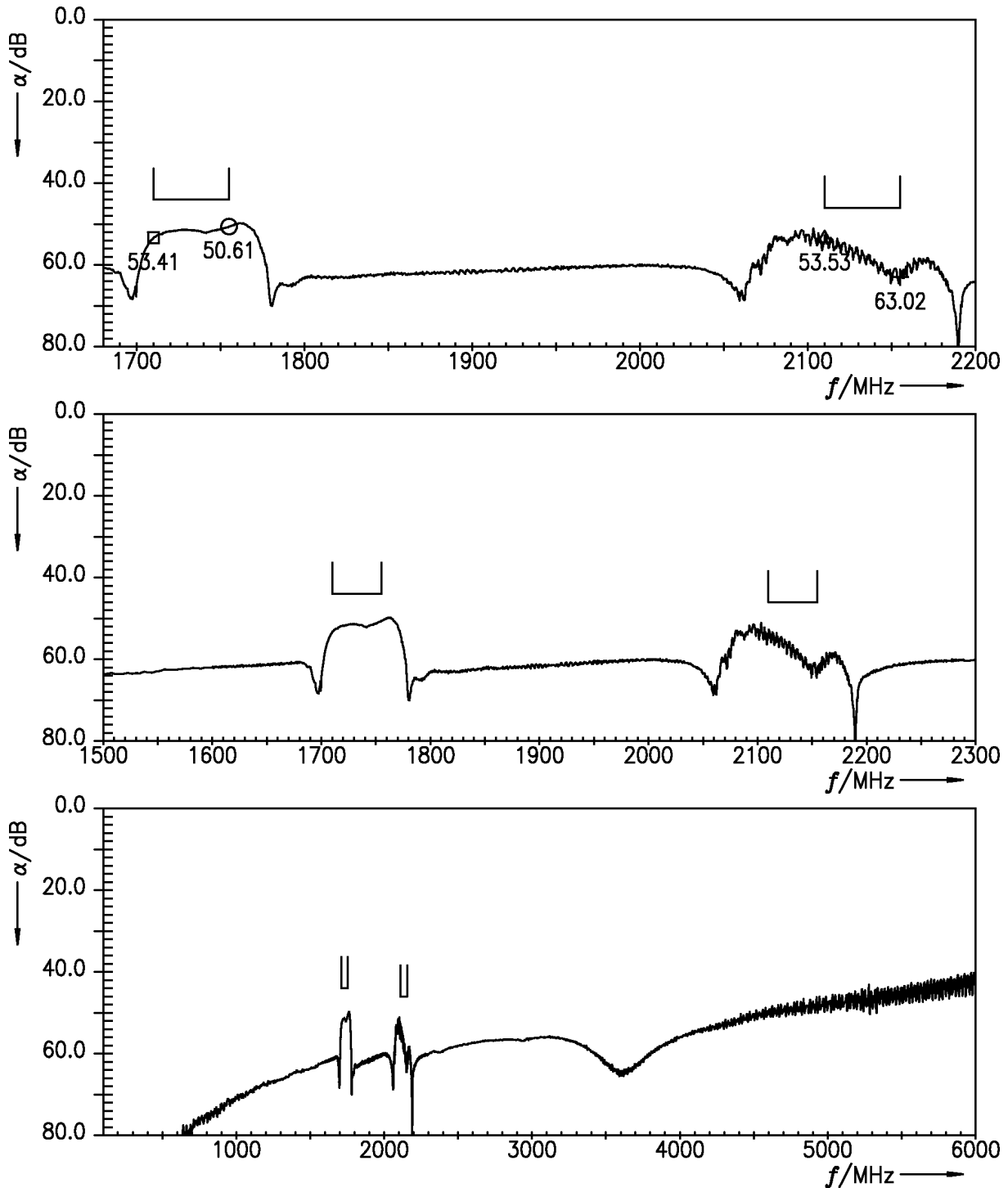


Figure 6: Isolation TX – RX.

Data sheet

9 Reflection coefficients

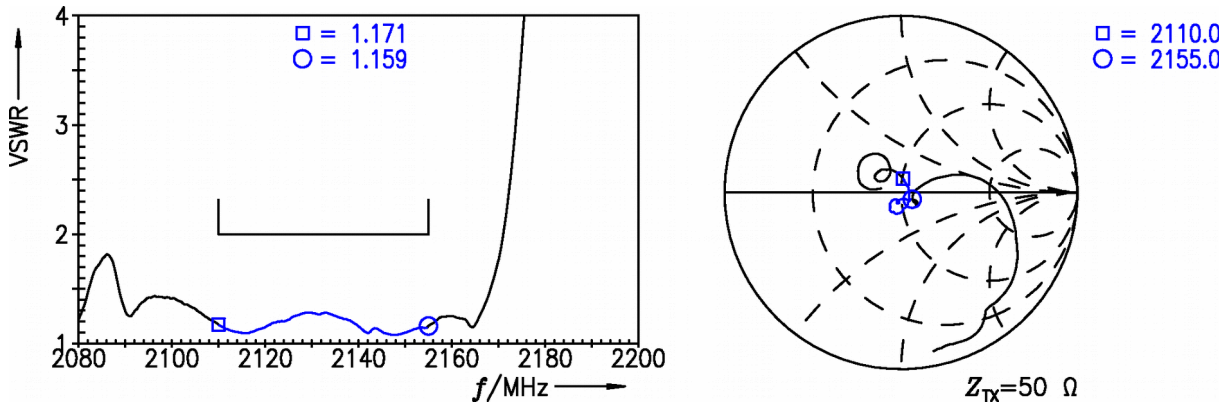


Figure 7: Reflection coefficient at TX port.

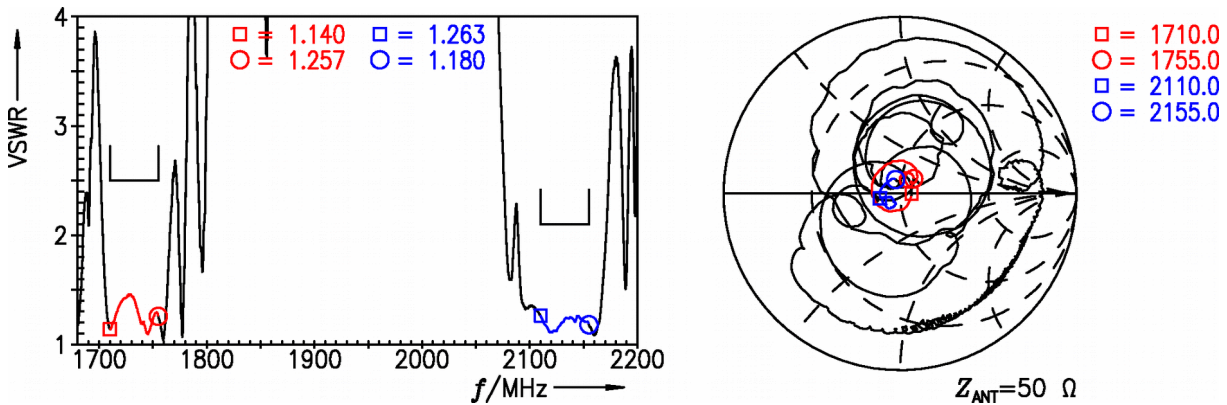


Figure 8: Reflection coefficient at ANT port.

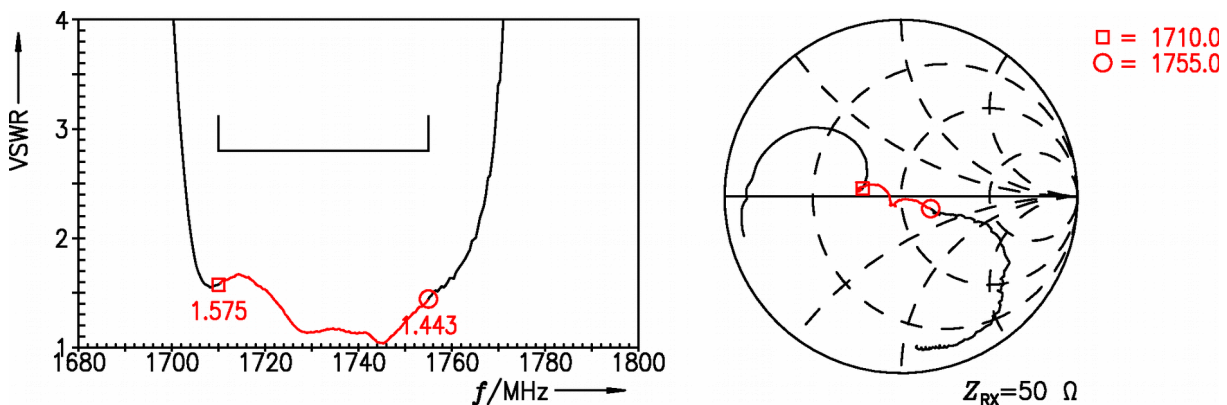


Figure 9: Reflection coefficient at RX port.

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10 EVMs

10.1 TX – ANT

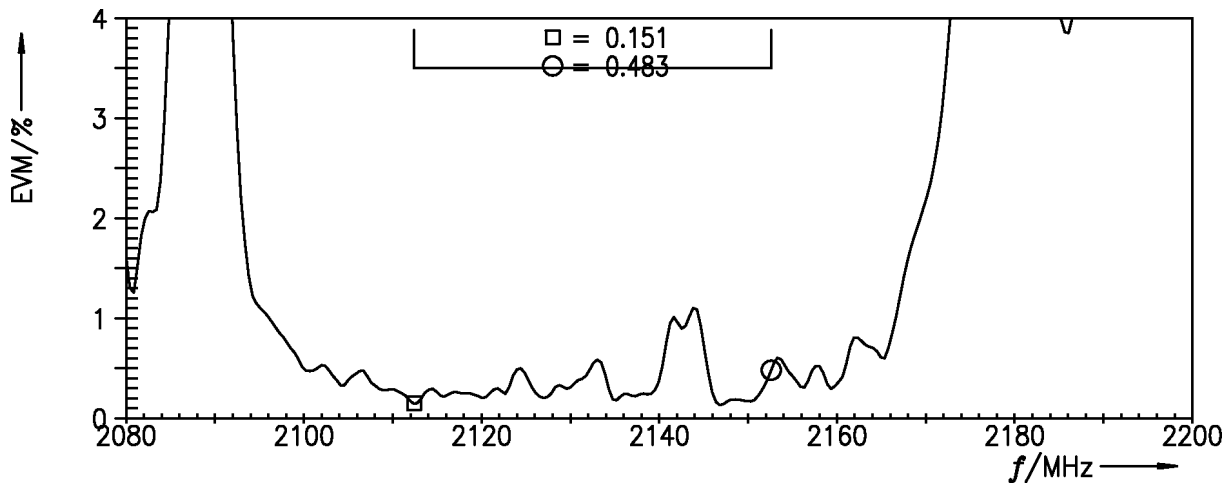


Figure 10: Error vector magnitude TX – ANT.

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10.2 ANT – RX

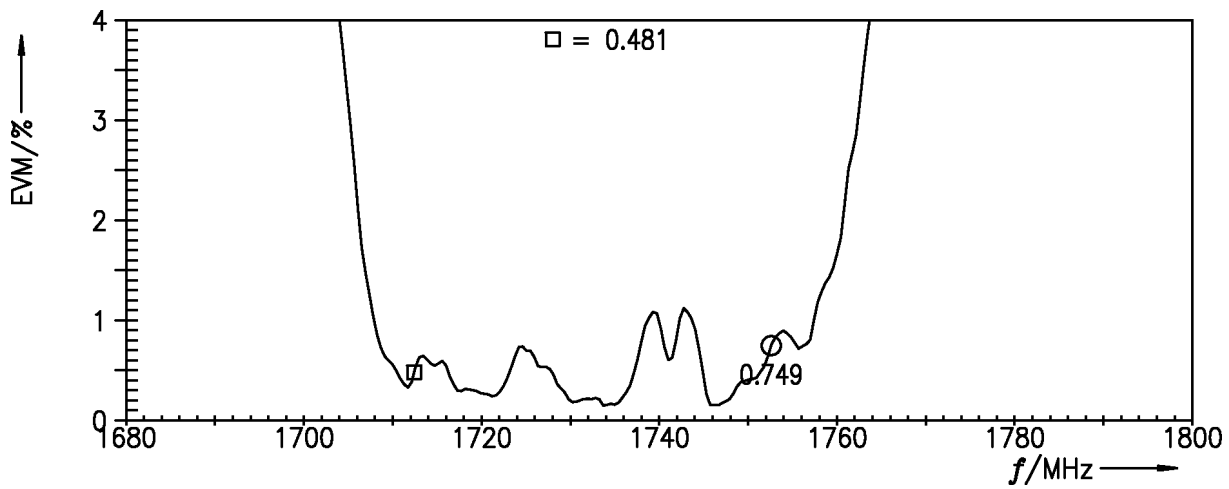


Figure 11: Error vector magnitude ANT – RX.

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SAW duplexer **1732.50 / 2132.50 MHz**

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11 Packing material

11.1 Tape

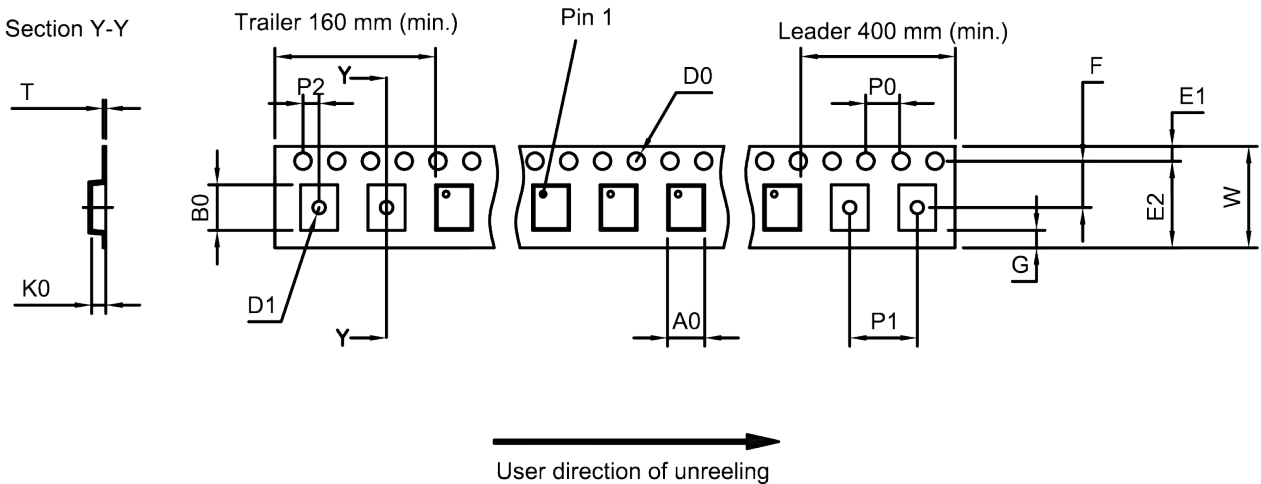


Figure 12: Drawing of tape (first-angle projection) with tape dimensions according to Table 1.

A ₀	2.25±0.05 mm	E ₂	6.25 mm (min.)	P ₁	4.0±0.1 mm
B ₀	2.75±0.05 mm	F	3.5±0.05 mm	P ₂	2.0±0.05 mm
D ₀	1.5+0.1/-0 mm	G	0.75 mm (min.)	T	0.25±0.03 mm
D ₁	1.0 mm (min.)	K ₀	0.6±0.05 mm	W	8.0+0.3/-0.1 mm
E ₁	1.75±0.1 mm	P ₀	4.0±0.1 mm		

Table 1: Tape dimensions.

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11.2 Reel with diameter of 180 mm

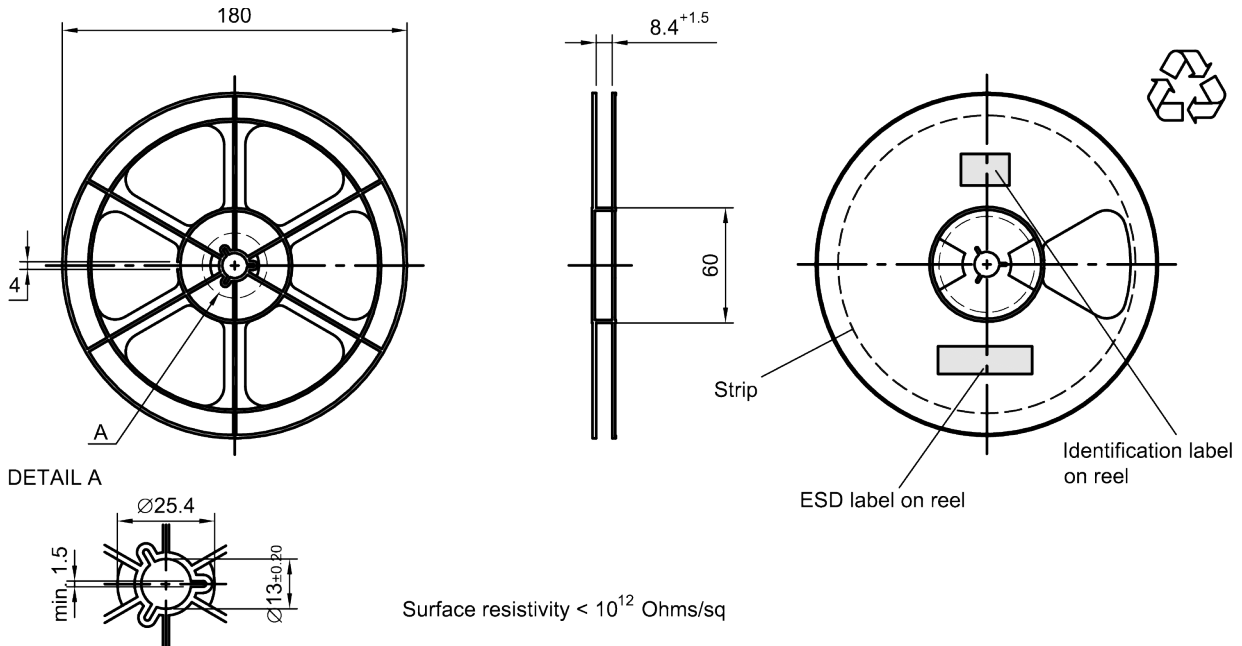


Figure 13: Drawing of reel (first-angle projection) with diameter of 180 mm.

Dimensions [mm]

X = 220+5

Y = 235+5

Sealing area 10±3

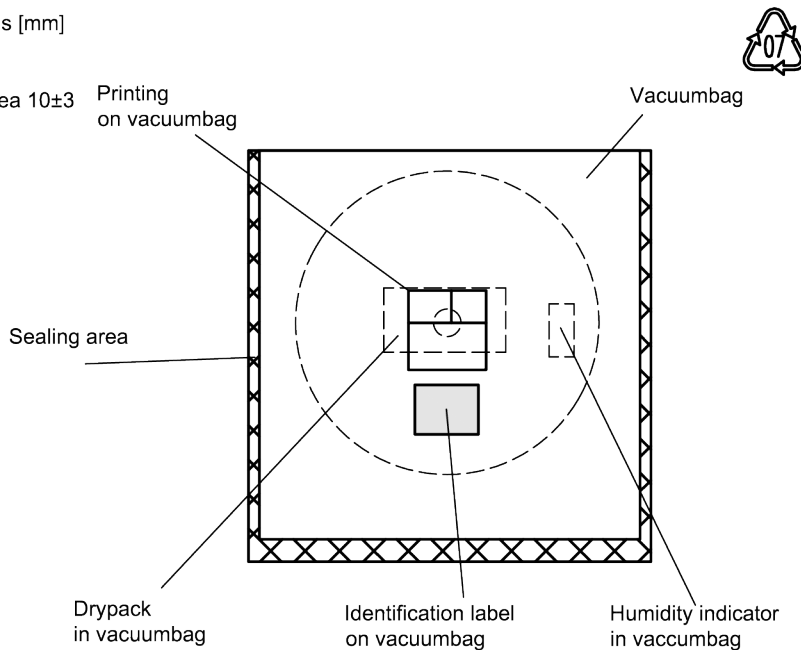


Figure 14: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

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Dimensions [mm]
 L = 188
 B = 188
 H = 30
 Tolerance ±5

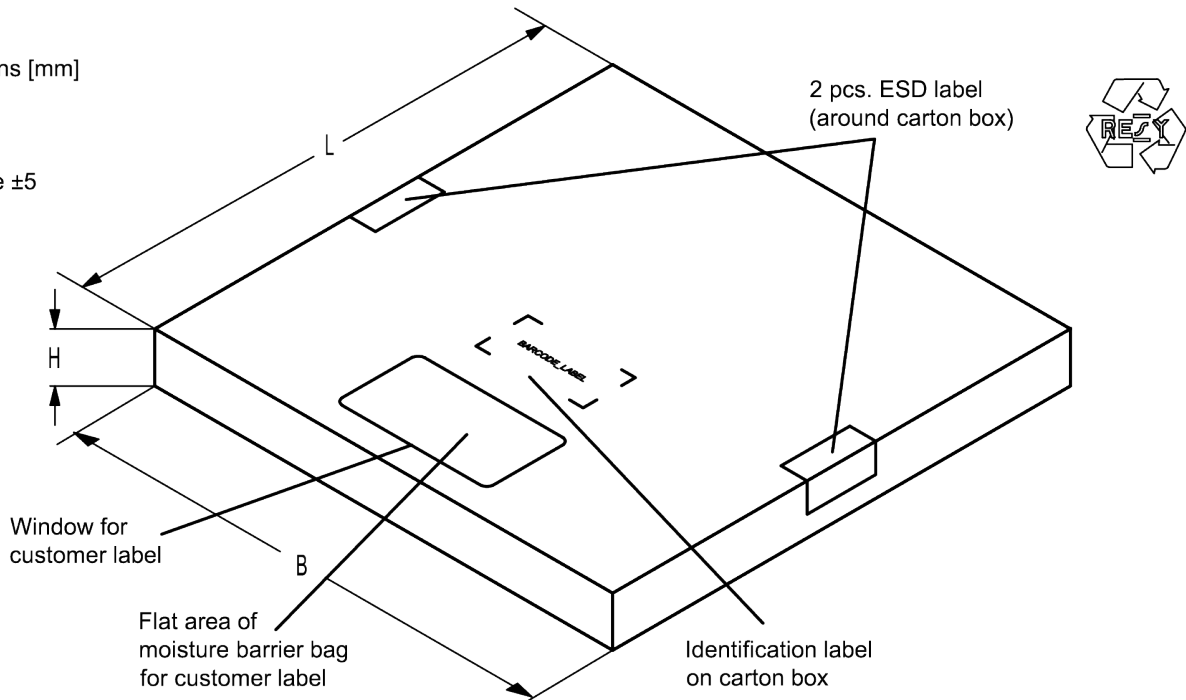


Figure 15: Drawing of folding box for reel with diameter of 180 mm.

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12 Marking

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx,
is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding	type number marking on device	in decimal code.
	16J	1234
	$1 \times 32^2 + 6 \times 32^1 + 18 (=J) \times 32^0$	1234

The BASE32 code for product type B8033 is 7V1.

■ Lot number:

The last 5 digits of the lot number, e.g., **12345**,
are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device		in decimal code.
5UY	$=>$	12345
$5 \times 47^2 + 27 (=U) \times 47^1 + 31 (=Y) \times 47^0$	$=$	12345

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	H
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	P
7	7	23	Q
8	8	24	R
9	9	25	S
10	A	26	T
11	B	27	V
12	C	28	W
13	D	29	X
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal value	Base47 code	Decimal value	Base47 code
0	0	24	R
1	1	25	S
2	2	26	T
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	B	35	f
12	C	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	H	41	\
18	J	42	?
19	K	43	{
20	L	44	}
21	M	45	<
22	N	46	>
23	P		

Table 2: Lists for encoding and decoding of marking.

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13 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
$T > 220$ °C	30 s to 70 s
$T > 230$ °C	min. 10 s
$T > 245$ °C	max. 20 s
$T \geq 255$ °C	–
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

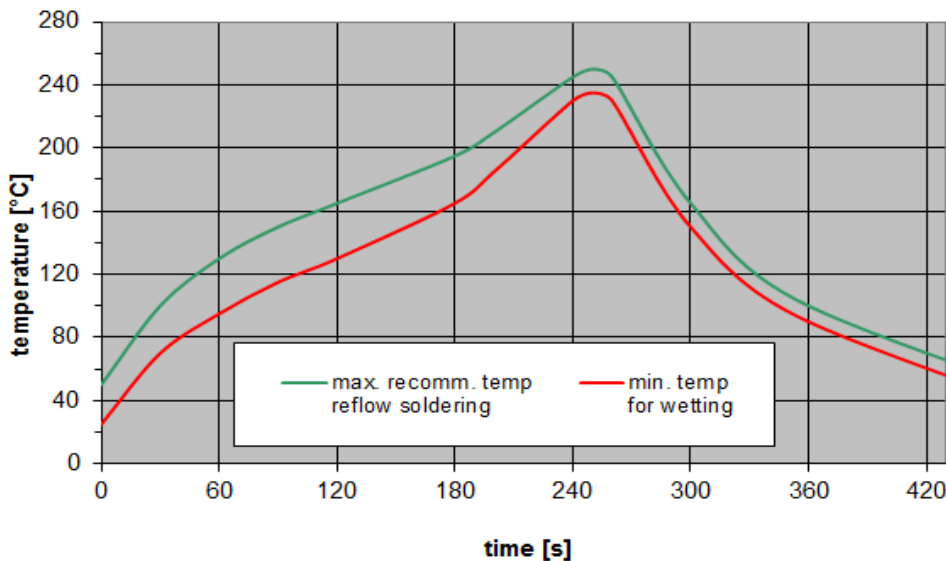


Figure 16: Recommended reflow profile for convection and infrared soldering – lead-free solder.

Data sheet

14 Annotations

14.1 Matching coils

See TDK inductor pdf-catalog <http://www.tdk.co.jp/tefe02/coil.htm#aname1> and Data Library for circuit simulation <http://www.tdk.co.jp/etvcl/index.htm>.

14.2 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

14.3 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

14.4 Ordering codes and packing units

Ordering code	Packing unit
B39212B8033P810	5000 pcs

Table 4: Ordering codes and packing units.